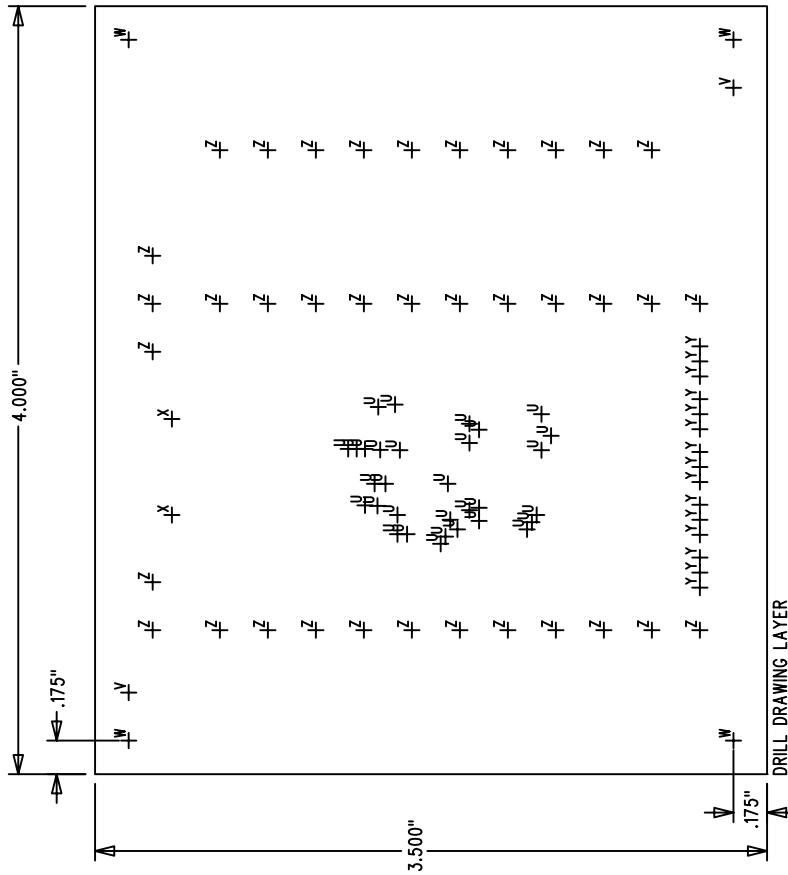


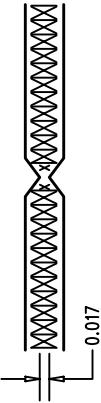
REV	REVISIONS	APPR	DATE
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ART01 = LAYER 1 ( COMPONENT SIDE )  
 ART02 = LAYER 2 ( SOLDER SIDE )

**NOTES : Unless Otherwise Specified**

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD THICKNESS .062 +/- .006 TOTAL OF 2 LAYERS
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE ELECTRODEPOSITED TIN-LEAD COMPOSITION BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC)
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT
4. SILSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK
5. ALL DIMENSIONS ARE IN INCHES
6. SCORING:



Fabrication Drawing

<b>APPROVALS</b>	LINEAR TECHNOLOGY		
	DRAWN	INIT	DATE
	CHECK		
	DESIGN		
	ENGR		
Size:	Demo Board:	DC497A	Rev.
None			
Scale = None			Sht: 1 of 1